



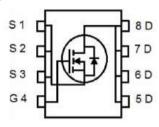
MJ P-Channel Super Trench Power MOSFET

Description

The MJXP40PT15G uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

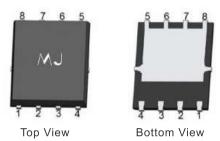
- $ightharpoonup V_{DS}$ =-40V,I_D=-150A R_{DS(ON)}=2.8mΩ (typical) @ V_{GS}=-10V R_{DS(ON)}=3.8mΩ (typical) @ V_{GS}=-4.5V
- ◆ Excellent gate charge x R_{DS(on)} product(FOM)
- ◆ Very low on-resistance R_{DS(on)}
- ◆ 150°C operating temperature
- ◆ Pb-free lead plating
- ♦ 100% UIS tested



Schematic Diagram

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification



DFN 5X6

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJXP40PT15G	MJXP40PT15G	DFN5X6-8L	4	-	2

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-40	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-150	Α
Drain Current-Continuous(Tc =100°C)	ID(100°C)	-106	А
Pulsed Drain Current	Ідм	-600	А
Maximum Power Dissipation	PD	150	W
Derating factor		1.2	W/°C
Single pulse avalanche energy (Note 5)	Eas	1076	mJ
Operating Junction and Storage Temperature Range	Тл,Тsтg	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rөjc	0.83	°C/W
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Electrical Characteristics (Tc=25℃ unless otherwise noted)

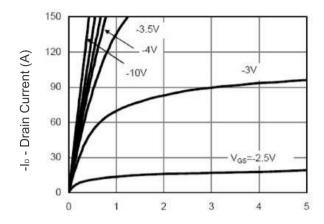
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =-250µA	-40	-	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =-40V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =-250μA	-0.8	-1.2	-1.8	V
Ducin Course On Chata Registeres	Passau	Vgs=-10V,lp=-75A	-	2.8	3.4	mΩ
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =-4.5V,I _D =-75A	_	3.8	4.6	mΩ
Forward Transconductance	grs	V _{DS} =-5V,I _D =-75A	-	30	-	S
Dynamic Characteristics (Note 4)	1		1			
Input Capacitance	Clss		-	8940	-	PF
Output Capacitance	Coss	V _{DS} =-20V,V _{GS} =0V F=1.0MHz	-	1900	-	PF
Reverse Transfer Capacitance	Crss		-	45	-	PF
Switching Characteristics (Note 4)	-		1			
Turn-on Delay Time	t _{d(on)}		-	18	-	nS
Turn-on Rise Time	tr	V _{DD} =-20V,I _D =-75A V _{GS} =-10V,R _G =1.6Ω	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}		-	90	-	nS
Turn-Off Fall Time	tr		-	15	-	nS
Total Gate Charge	Qg		-	104.4	-	nC
Gate-Source Charge	Qgs	V _{DS} =-20V,I _D =-75A V _{GS} =-10V	_	20.8	_	nC
Gate-Drain Charge	Qgd	VGS=-IUV	_	13.5	-	nC
Drain-Source Diode Characteristics						<u> </u>
Diode Forward Voltage (Note 3)	Vsp	V _{GS} =0V,I _S =-75A	_	-	-1.2	V
Diode Forward Current (Note 2)	Is		_	_	-150	Α
Reverse Recovery Time	trr		_	_	35	nS
Reverse Recovery Charge	Qrr	TJ=25°C,IF=-75A di/dt= 100A/µs (Note 3)		_	85	nC
Neverse Necovery Charge	Q _{rr}		_	_	00	110

Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production
- \odot EAS condition : Tj=25 $^{\circ}$ C,VDD=-20V,VG=-10V,L=0.5mH,Rg=25 Ω

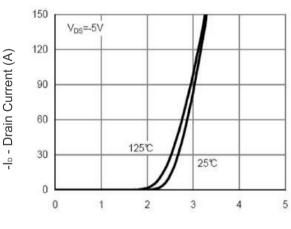


Typical Electrical and Thermal Characteristics



-Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



-Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

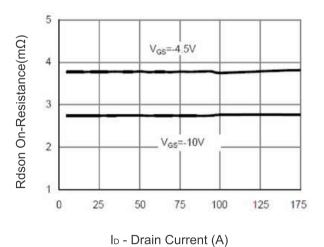
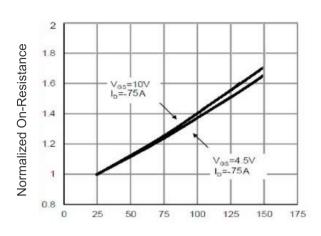
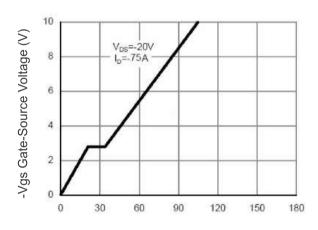


Figure 3 Rdson- Drain Current

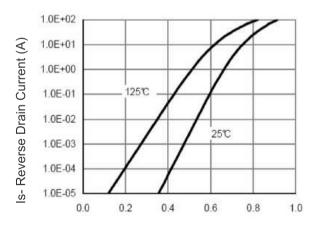


T_J-Junction Temperature (°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



1.0

0.1

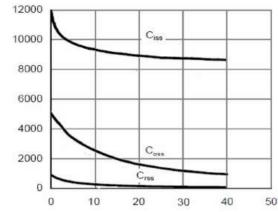
0.0

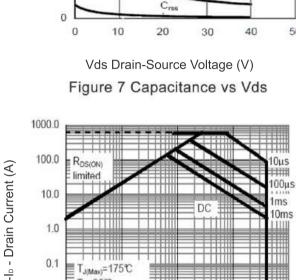
0.01

T_{J(Max)}=175℃ T_c=25℃

0.1

Capacitance (pF)



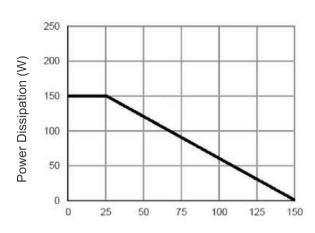


-Vds Drain-Source Voltage (V)

1

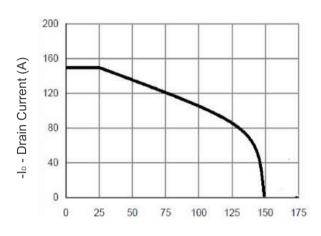
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Figure 8 Safe Operation Area



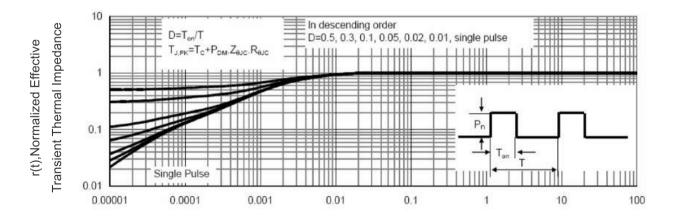
T_J-Junction Temperature(°C)

Figure 9 Power De-rating



T_J-Junction Temperature(°C)

Figure 10 Current De-rating



1ms 10ms

100

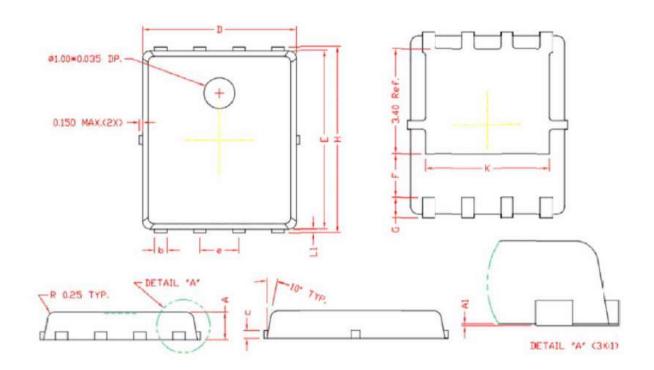
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





DFN5X6-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NCM	MAX	
A	0.80	0.90	1.00	
Al	0.00	0.03	0.05	
ь	0.35	0.42	0.49	
c	0. 254 REF.			
D	4.90	5.00	5. 10	
F	1. 40 REF.			
E	5. 70	5.80	5. 90	
е	1. 27 BSC.			
H	5. 95	6.08	6. 20	
Ll	0.10	0.14	0.18	
G	0. 60 REF.			
K	4. 00 REF.			





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